

BS EN 61189-3-719:2016



BSI Standards Publication

Test methods for electrical materials, printed boards and other interconnection structures and assemblies

Part 3-719: Test methods for interconnection structures (printed boards) — Monitoring of single plated-through hole (PTH) resistance change during temperature cycling

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National foreword

This British Standard is the UK implementation of EN 61189-3-719:2016. It is identical to IEC 61189-3-719:2016.

The UK participation in its preparation was entrusted to Technical Committee EPL/501, Electronic Assembly Technology.

A list of organizations represented on this committee can be obtained on request to its secretary.

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Published by BSI Standards Limited 2016

ISBN 978 0 580 85142 1

ICS 31.180

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This Published Document was published under the authority of the Standards Policy and Strategy Committee on 30 April 2016.

Amendments/corrigenda issued since publication

Date	Text affected
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EUROPEAN STANDARD
NORME EUROPÉENNE
EUROPÄISCHE NORM

EN 61189-3-719

April 2016

ICS 31.180

English Version

**Test methods for electrical materials, printed boards and other
interconnection structures and assemblies - Part 3-719: Test
methods for interconnection structures (printed boards) -
Monitoring of single plated-through hole (PTH) resistance
change during temperature cycling
(IEC 61189-3-719:2016)**

Méthodes d'essai pour les matériaux électriques, les cartes
imprimées et autres structures d'interconnexion et
ensembles - Partie 3-719: Méthodes d'essai pour les
structures d'interconnexion (cartes imprimées) - Contrôles
de la variation de résistance des trous métallisés uniques
(PTH) au cours des cycles thermiques
(IEC 61189-3-719:2016)

Prüfverfahren für Elektromaterialien, Leiterplatten und
andere Verbindungsstrukturen und Baugruppen - Teil 3-
719: Prüfverfahren für Verbindungsstrukturen (Leiterplatten)
- Überwachung des Widerstands von
Einzeldurchkontaktierungen (PTH - plated-through hole) bei
Temperaturwechselbeanspruchung
(IEC 61189-3-719:2016)

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European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

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European foreword

The text of document 91/1303/FDIS, future edition 1 of IEC 61189-3-719, prepared by IEC/TC 91 "Electronics assembly technology" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN 61189-3-719:2016.

The following dates are fixed:

- latest date by which the document has to be (dop) 2016-11-09
implemented at national level by
publication of an identical national
standard or by endorsement
- latest date by which the national (dow) 2019-02-09
standards conflicting with the
document have to be withdrawn

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The text of the International Standard IEC 61189-3-719:2016 was approved by CENELEC as a European Standard without any modification.

Annex ZA

(normative)

**Normative references to international publications
with their corresponding European publications**

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 When an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cenelec.eu.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60068-2-14	-	Environmental testing -- Part 2-14: Tests - Test N: Change of temperature	EN 60068-2-14	-
IEC 60068-2-58	2015	Environmental testing - Part 2-58: Tests - Test Td: Test methods for solderability, resistance to dissolution of metallization and to soldering heat of surface mounting devices (SMD)	EN 60068-2-58	2015
IEC 60194	-	Printed board design, manufacture and assembly - Terms and definitions	EN 60194	-
IPC-2221	-	Generic Standard on Printed Board Design -		-

CONTENTS

FOREWORD	3
1 Scope	5
2 Normative references	5
3 Terms and definitions	5
4 Test specimens	5
5 Test apparatus	6
5.1 Reflow equipment	6
5.2 Temperature cycling chamber	6
5.3 Electrical resistance recording	6
6 Procedure.....	7
6.1 Preconditioning	7
6.2 Temperature cycling test.....	8
7 Report	9
8 Additional information	10
Bibliography.....	11
Figure 1 – Example photograph of a section of a test coupon for a six-layer PCB	6
Figure 2 – Principle of online resistance measurement with high currents	7
Figure 3 – Reflow temperature profile for PCB preconditioning	8
Table 1 – Details of the reflow temperature profile for PCB preconditioning	8